

pSEMI MATERIAL DECLARATION FORM

Product:	PE42448
Ordering Codes:	PE42448A-Z
Description:	SP4T switch
Package:	20-lead 4x4 mm LGA
Environmental Compliance	EU RoHS Directive 2011/65/EC and amendment 2015/863, REACH - EU ECHA SVHC, Arsenic Free , JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
Lead Finish	NiPdAu
Availability	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Silicon	7440-21-3	7.798858	22.18%	221,758.23
Die	Phosphorus	7723-14-0	0.000039	0.00%	1.12
Die	Boron	7440-42-8	0.000039	0.00%	1.12
Die	Arsenic	7440-38-2	0.000039	0.00%	1.12
Die	Germanium	7440-56-4	0.000039	0.00%	1.12
Die	Indium	7440-74-6	0.000039	0.00%	1.12
Die	Cobalt	7440-48-4	0.000039	0.00%	1.12
Die	Tungsten	7440-33-7	0.001468	0.00%	41.73
Die	Copper	7440-50-8	0.044506	0.13%	1,265.51
Die	Tantalum	7440-25-7	0.002111	0.01%	60.03
Die	Aluminum	7429-90-5	0.000816	0.00%	23.21
Polyimide	Proprietary	-	0.054780	0.16%	1,557.65
UBM	Copper	7440-50-8	0.000314	0.00%	8.94
UBM	Titanium	7440-32-6	0.002044	0.01%	58.12
Pillar - Solder Cap	Tin	7440-31-5	0.019904	0.06%	565.98
Pillar - Solder Cap	Silver	7440-22-4			
Pillar - Cu	Copper	7440-50-8	0.221626	0.63%	6,301.86
Pillar - Ni Barrier	Nickel	7440-02-0	0.012950	0.04%	368.22
Substrate	Copper	7440-50-8	1.658762	4.72%	47,166.42
Substrate	Gold	7440-57-5	0.008706	0.02%	247.55
Substrate	Palladium	7440-05-3	0.014057	0.04%	399.70
Substrate	Nickel	7440-02-0	0.327408	0.93%	9,309.76
Substrate	Copper	7440-50-8	1.932539	5.50%	54,951.17
Substrate	Thermosetting resin	-	6.080000	17.29%	172,883.01
Substrate	Glass cloth	65997-17-3	6.080000	17.29%	172,883.01
Substrate	Plastics PAK	Trade secret	0.196604	0.56%	5,590.39
Substrate	Barium sulphate	7727-43-7	0.129732	0.37%	3,688.90
Substrate	Plastics EP	-	0.087380	0.25%	2,484.62
Substrate	Talc	14807-96-6	0.013374	0.04%	380.30
Substrate	Natural Ingredient, not to declare	-	0.006687	0.02%	190.15
Substrate	Additives, not to declare	-	0.006687	0.02%	190.15
Substrate	Silicon dioxide	7631-86-9	0.002675	0.01%	76.06
Substrate	Pigment portion, not to declare	-	0.002675	0.01%	76.06
Mold CMPD	Solid Epoxy Resin	-	0.627684	1.78%	17,848.00
Mold CMPD	Hardener	-	0.366149	1.04%	10,411.33
Mold CMPD	Carbon Black	1333-86-4	0.052307	0.15%	1,487.33
Mold CMPD	Metal Hydroxide	-	0.209228	0.59%	5,949.33
Mold CMPD	Amorphous silica	60676-86-0	9.206025	26.18%	261,770.62
Total Weight (mg)			35.168292	100.00%	1,000,000